



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC016N06NS		<b>Issued</b>		1. August 2018	
<b>MA#</b>				MA001341332					
<b>Package</b>				PG-TDSON-8-17		<b>Weight*</b>		119.80 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.517	1.27	1.27	12665	12665	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95		
	non noble metal	iron	7439-89-6	0.038	0.03		316		
	non noble metal	copper	7440-50-8	37.762	31.52	31.56	315214	315625	
	noble metal	gold	7440-57-5	0.045	0.04	0.04	372	372	
wire	organic material	carbon black	1333-86-4	0.130	0.11		1088		
encapsulation	plastics	epoxy resin	-	5.085	4.24		42448		
	inorganic material	silicondioxide	60676-86-0	38.247	31.93	36.28	319269	362805	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12118	12118	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1382	1382	
solder	non noble metal	tin	7440-31-5	0.042	0.04		351		
	noble metal	silver	7440-22-4	0.053	0.04		439		
	non noble metal	lead	7439-92-1	2.010	1.68	1.76	16782	17572	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
heatspreader	non noble metal	zinc	7440-66-6	0.013	0.01		112		
	non noble metal	iron	7439-89-6	0.269	0.22		2243		
	non noble metal	copper	7440-50-8	10.909	9.11	9.34	91063	93446	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
heat sink CLIP	non noble metal	zinc	7440-66-6	0.026	0.02		221		
	non noble metal	iron	7439-89-6	0.529	0.44		4416		
	non noble metal	copper	7440-50-8	21.482	17.93	18.40	179323	184015	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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